

Future Technology Devices International Limited Practical USB Interface Solutions

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Product Change Notification: For Limited Distribution

Product Part Number	Vinculum-II devices: VNC2-32Q1B, VNC2-32L1B, VNC2-48L1B, VNC2-64L1B	Estimated implementation date
Description of Change	Device revised from Revision B to Revision C	July 2016
Reason for Change	To improve ESD susceptibility.	
Detailed Description	The grounding, within the package of the VNC2 device, has been modified to improve its ESD susceptibility.	
Impact to Data sheet	See Revision History of Datasheet	
Benefit of Change	Improved tolerance to ESD, resulting in higher quality of devices.	
Markings to distinguish revised from:	Devices will be marked as with a "C" to indicate Revision C: VNC2-32Q1C, VNC2-32L1C, VNC2-48L1C, VNC2-64L1C	
Sample Availability	July 2016 (VNC2-32Q1C was released in the Mar of 2016)	
Risk Assessment, Fit Form and Function & reliability	Fit: package dimensions are unchanged Form: visual appearance is unchanged Function: Functional silicon has not changed.	
PDF Download	http://www.ftdichip.com/Support/Documents/ProductChangeNotifications/PCN_FT_022.pdf	

Others:

The Vinculum-II VNC2 Revision B and VNC2 Revision C silicon is exactly the same. There are no functional changes to the IC. Pin 8 updated from Test to NC